



22.	(Amended)	The method of claim 18, further comprising thermally coupling the heat sink	
to a di	e.		
23.	(Canceled)		
24.	(Amended)	The method of claim 19, where n the elevated temperature is greater than 850	
degree	es Fahrenheit an	ad the cryogenic temperature is approximately -327 degrees Fahrenheit.	
25.	(Amended)	The method of claim 20, wherein said lowering comprises placing the heat	
sink in	a bath of liqui	d nitrogen.	
26.	(New) A meta	hod comprising:	
	providing a he	at sink of a material having a grain size increased by heating of the material to	
improve thermal conductivity of the heat sink and			
	subjecting the	heat sink to a cryogenic temperature to strengthen the material.	
27.	(New) A metl	hod comprising:	
	providing a he	eat sink for coupling to a die, the heat sink of a material having a first grain	
size; and			
	increasing the	first grain size to a second grain size to enhance the thermal conductivity of	
the hea	he heat sink.		
28.	(New) A meth	hod comprising:	
	re-crystallizing	g an alloy material of a heat sink to improve a thermal conductivity of the heat	
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